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## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Splication No.: Udayakumar et al.

Ťiled:

10/620,516 July 16, 2003

For:

HYDROGEN BARRIER FOR PROTECTING FERROELECTRIC CAPACITORS IN A SEMICONDUCTOR DEVICE AND METHODS

FOR FABRICATING THE SAME

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

1. Pursuant to 37 C.F.R. 1.97 and 1.98, and in compliance with 37 C.F.R. 1.56, the Office's attention is

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

1449. A copy previously cite	patents, pending applications, publications and other information listed on the attached PTO- of each listed document is enclosed except for: (a) pending applications or (b) those d or submitted to the Office in the following application(s) upon which this application relies for g date under 35 U.S.C. 120:
Serial No.: Filing Date	
PTO-1449, Aptreated accord	y document, publication or other information for which a date is not given on the attached oplicant(s) believe(s) the same may qualify as "prior" art to this application and should be dingly, although Applicant(s) reserve(s) the right to contest the prior art status of any oblication or information, should issue arise.
accompanies	ng each listed document that is not in the English language, an English-language translation this Statement as indicated on the attached PTO-1449 or a concise explanation of the document is set forth in the following document(s):
(a)	Copy of each English language version of a search report indicating the degree of relevance found by the foreign office of each document being submitted from the search report.
(b)	Attachment entitled "Concise Explanation of Relevance of Non-English Language Documents".
3. Pursuar	t to 37 C.F.R. 1.97(b) this Statement is being filed (one must be checked):
(a) <u>X</u>	Within 3 months of the filing date or date of entry into the National Stage.
(b)	Before the mailing date of a first Office Action on the merits. If this Statement is not filed before the mailing date of a first Office Action on the merits, the required certification is given below or, in the absence thereof, the Office is authorized to charge the required fee set forth in 37 C.F.R. 1.17(p) to Deposit Account No. 20-0668 for consideration of this Statement

Before the mailing date of a first Office Action on the merits after a first or second

submission under 37 C.F.R. 1.129(a).

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12	Substitute for	Form 1449A/PTO		Application Number	10/620,516		
	INFORMATIO	N DISCLOSURE		Filing Date	July 16, 2003		
5		BY APPLICANT		First Named Inventor	Udayakumar et al.		
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		U.S. Patent Do	ocument	Name of Patentee or	Date of Pub. of		
Exam. Initials*	Cite No.1	Number	Kind Code <sup>2</sup> (if known)	Applicant of Cited Doc.	Cited Doc. (mm-dd-yyyy)	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	
_	AA	6,144,060		Park et al.	11/07/2000	Entire Document	
	AB	6,225,656	B1	Cuchiaro et al.	05/01/2001	Entire Document	
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		Foreign Patent Document		Name of Patentee	Date of Pub.			
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		OTHER PRIOR ART - NON PATENT LITERATURE DOCUMENTS	
Exam. Initials*	Cite No.1	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T <sup>2</sup>
	CA	Notes taken at the International Symposium on Applications of Ferroelectrics Conference in Nara, Japan in May, 2002. The speaker was H. Nagel of Infineon Technologies and Toshiba Corporation, Key Technologies for High Density FeRAM Application, one page.	
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Examiner	Date	
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US and Foreign Patent Documents: <sup>1</sup>Unique citation designation number. <sup>2</sup>See attached Kinds of U.S. Patent Documents. <sup>3</sup>Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). 4For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. 5Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. 6Applicant is to place a check mark here if English language Translation is attached.

Other Prior Art/Non-Patent Literature Documents: 1 Unique citation designation number. 2 Applicant is to place a check mark here if English Translation is attached.

<sup>\*</sup>EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.



Notes taken at the International Symposium on Applications of Ferroelectrics Conference in Nara, Japan. The Speaker was H. Nagel of Infineon Technologies and Toshiba Corporation, Key Technologies for High Density FeRAM Application on May, 2002.

He gave a general overview of the status of integration issues with no stress on PZT or SBT talking about issues like deposition temperature, polarization,  $H_2$  barriers. They are using W plugs and vias. Comments on  $H_2$  diffusion barriers:

LPCVD SiN is a good diffusion barrier, but capacitors got damaged during deposition. They used a  $SiO_2$  buffer layer prior to SiN deposition, which solved their problem. He did not answer how thick  $SiO_2$  films were used. Other barriers used in the filed include  $Al_2O_3$ , SiON,  $TiO_2/SiO_2$ . He ended with some data on 8Mb arrays - Chip size < 76mm2;

CMOS:  $0.25~\mu m$ ; Capacitor area  $0.9x0.95~\mu m$ ; cell area  $5.1~\mu m^2$ ; chain cell structure. He showed bit distribution using PZT films with a separation of 1.03V; no fatigue up to  $10^{11}$  cycles as measured by amp signal, zeros at 1600~mV and ones at 2600~mV.